

## C0805X223J5RACTU

Aliases (C0805X223J5RAC7800) SMD Comm X7R Flex, Ceramic, 0.022 uF, 5%, 50 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 0805, 0.6 mm



Click here for the 3D model.

General Information		
Series	SMD Comm X7R Flex	
Style	SMD Chip	
Description	SMD, MLCC, FT-CAP, Temperature Stable	
Features	FT-CAP, Temperature Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	13 mg	
Shelf Life	78 Weeks	
MSL	1	

Time is 1000 Hours

45.4545 GOhms

	Specifications	
0805	Capacitance	0.022 uF
2mm +/-0.3mm	Measurement Condition	1 kHz 1.0Vrms
1.25mm +/-0.3mm	Tolerance	5%
0.78mm +/-0.20mm	Voltage DC	50 VDC
0.6mm MIN	Dielectric Withstanding Voltage	125 VDC
0.5mm +/-0.25mm	Temperature Range	-55/+125°C
	Temp. Coefficient	X7R
T&R, 180mm, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
4000	Dissipation Factor	2.5%1kHz1.0Vrms
	Aging Rate	3% Loss/Decade Hour: Referee

Insulation Resistance

W 1.25mm +/ Т 0.78mm + s 0.6mm MI в 0.5mm +/

## **Packaging Specifications** T&R, 180m Packaging

Dimensions

Chip Size

L

Packaging Quantity 4000

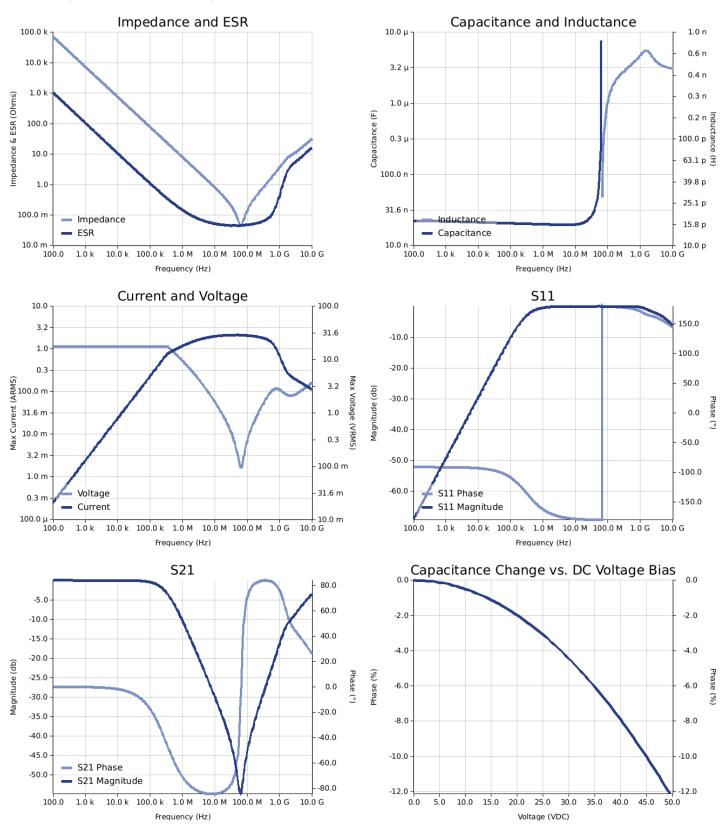
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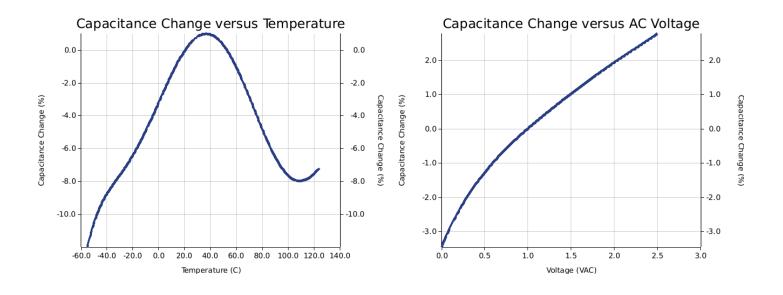
## Simulations

For the complete simulation environment please visit K-SIM.





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## These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
  The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
  The effects shown herein are based on measured data from a multiple part sample of the parts in question.
  Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.